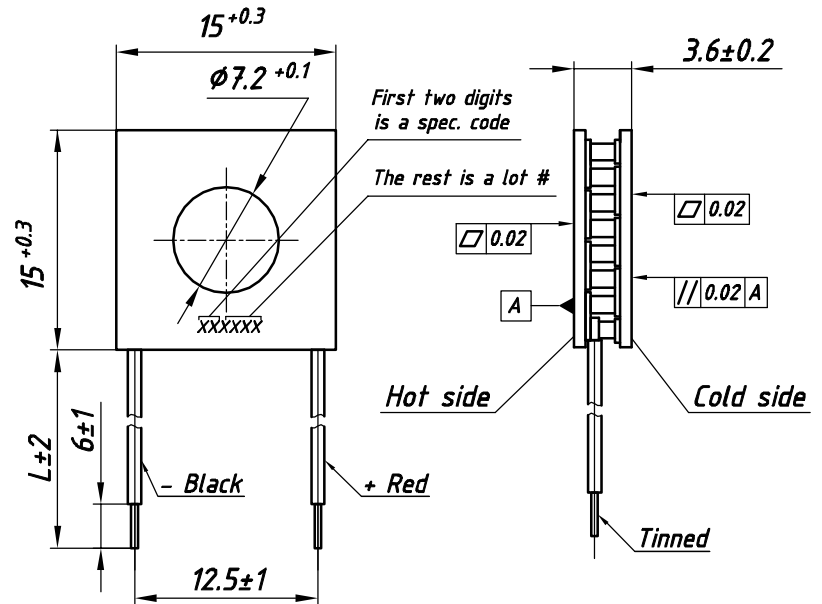


TECHNICAL DATA

U_{max}	2.6 V	$T_{hot}=25^{\circ}C$ Vacuum
Q_{max}	5.5 W	
ΔT_{max}	72°	
I_{max}	3.5 A	
ACR at 25°C	0.67 Ohm	
Pad type	Hot side	Ceramics Al_2O_3 , white 96%
	Cold side	
Max. processing temperature	Depends on chosen solder type	
Standard tolerances for thermal and electrical parameters $\pm 10\%$		

MODULE DRAWING
standard design



STANDARD ORDERING OPTIONS

Nº	Option	Parameter
1	Lead wires	AWG Nº
		20 22 24
		L - under customer request
2	Lead wires insulation	Type / Max. processing temp.
		Without insulation / See solder type m.p.t
		PVC-1 / 85° C
		PVC-2 / 105° C
		Silicone / 180° C
3	Internal solder	Type / Max. processing temp.
		Type-1 / 138° C
		Type-2 / 183° C *
		Type-3 / 227° C
		Type-4 / 232° C
4	Anticorrosional coating	yes no
5	Sealing	Type / Max. processing temp.
		Without sealing / 200° C
		Epoxy / 130° C
		Silicone / 180° C

AVAILABLE MODIFICATIONS

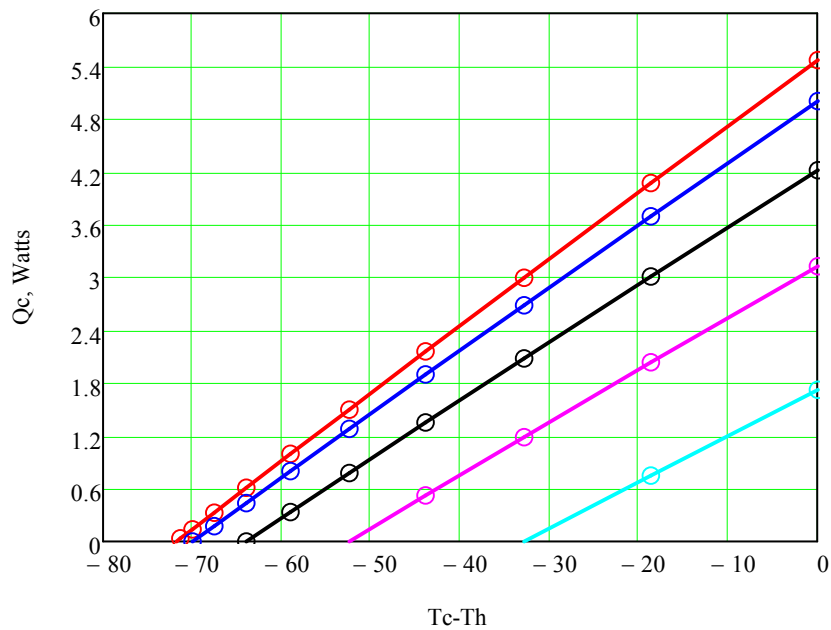
Design	Description
TM-23-1.0-3.0	

OPTIONS UPON REQUEST

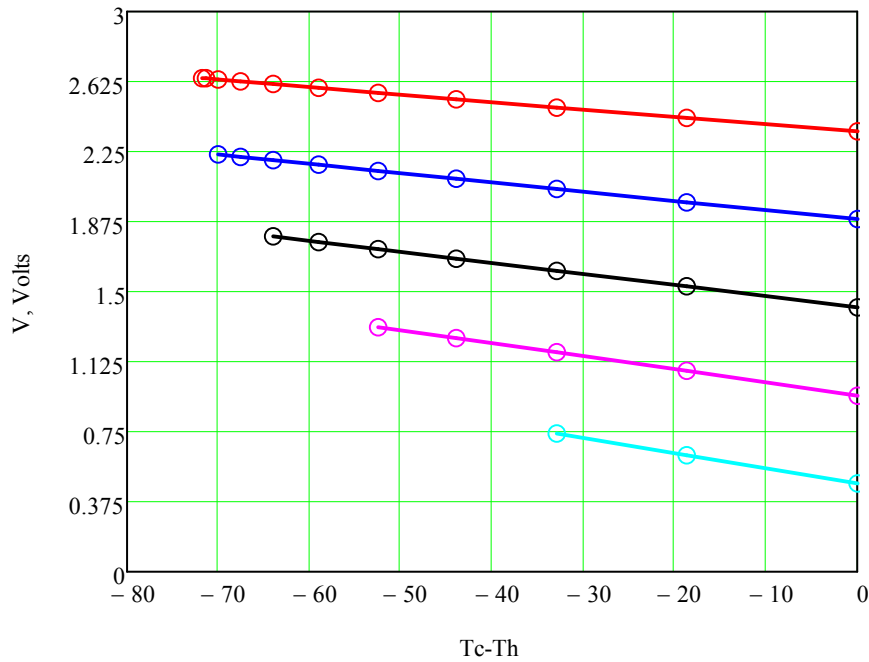
Height tolerance	± 0.02
Unflatness and nonparallelism	± 0.02

- Solder type marked * is not compliant to RoHS (2002/95/EC)
- For another options consult of our technical support engineers

Performance graphs for TM-23-1.0-3.0 module at Th=25 °C
Environment: vacuum



- I=Imax
- I=0.8Imax
- I=0.6Imax
- I=0.4Imax
- I=0.2Imax



- I=Imax
- I=0.8Imax
- I=0.6Imax
- I=0.4Imax
- I=0.2Imax